505403453 04/01/2019

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
TOMOHARU TANAKA	04/01/2019

RECEIVING PARTY DATA

Name:	MICRON TECHNOLOGY, INC.
Street Address:	8000 SOUTH FEDERAL WAY
Internal Address:	MS 525
City:	BOISE
State/Country:	IDAHO
Postal Code:	83716

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16371221

CORRESPONDENCE DATA

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Correspondent Name: DICKE, BILLIG & CZAJA, PLLC - MICRON

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ATTORNEY DOCKET NUMBER:	M3401.174.101	
NAME OF SUBMITTER:	MARK A. PETERSON	
SIGNATURE:	/Mark A. Peterson/	
DATE SIGNED:	04/01/2019	

Total Attachments: 2

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PATENT 505403453 REEL: 048750 FRAME: 0709

ASSIGNMENT

WHEREAS, I.

Tomoharu Tanaka, residing at 1-2-2-A907 Shinkoyasu Kanagawa-ku, Yokohama, Kanagawa 221-0013 JAPAN

made certain new and useful inventions and improvements for which I executed an application for Letters Patent of the United States herewith, and which is entitled CURRENT MONITORING IN SEMICONDUCTOR PACKAGES.

AND WHEREAS, Micron Technology, Inc., a corporation organized and existing under and by virtue of the laws of the State of Delaware, and having an office and place of business at 8000 South Federal Way, MS 525, Boise, Idaho, 83716, (hereinafter "Assignee") is desirous of acquiring the entire right, title and interest in and to said inventions, improvements and application and in and to the Letters Patent to be obtained therefor:

NOW, THEREFORE, to all whom it may concern, be it known that for good and valuable consideration, the receipt and sufficiency whereof is hereby acknowledged, I have sold, assigned, and transferred, and by these presents do sell, assign and transfer unto said Assignee, its successors or assigns, the entire right, title and interest for all countries in and to all inventions and improvements disclosed in the aforesaid application, and in and to the said application, all divisions, continuations, continuations-in-part, or renewals thereof, all Letters Patent which may be granted therefrom, and all reissues or extensions of such patents, and in and to any and all applications which have been or shall be filed in any foreign countries for Letters Patent on the said inventions and improvements, including an assignment of all rights under the provisions of the International Convention, and all Letters Patent of foreign countries which may be granted therefrom; and we do hereby authorize and request the Commissioner of Patents and Trademarks to issue any and all United States Letters Patent for the aforesaid inventions and improvements to the said Assignee as the assignee of the entire right, title and interest in and to the same, for the use of the said Assignee, its successors and assigns.

AND, for the consideration aforesaid, I do hereby agree that I and my respective executors and legal representatives will make, execute and deliver any and all other instruments in writing including any and all further application papers, affidavits, assignments and other documents, and will communicate to said Assignee, its successors and representatives all facts known to me relating to said improvements and the history thereof and will testify in all legal proceedings and generally do all things which may be necessary or desirable more effectually to secure to and vest in said Assignee, its successors or assigns the entire right, title and interest in and to the said improvements, inventions, applications, Letters Patent, rights, titles, benefits, privileges and advantages hereby sold, assigned and conveyed, or intended so to be.

AND, furthermore I covenant and agree with said Assignee, its successors and assigns, that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by me/us and that full right to convey the same as herein expressed is possessed by me.

PATENT REEL: 048750 FRAME: 0710 Docket No.: M3401.174.101 Serial No.: Unknown

Title:

Micron Docket No.: 2018-1852.00 US Filing Date: Herewith Page 2 of 2

IN TESTIMONY WHEREOF, I have hereunto s	set my hand this/_ day ofApril	<u> 20/9</u>
	omoharu Tanaka	,
WITNESS:		
Shigekazu Yamada Printed Name	Sligh Mulle Signature	
4/1/2019 (Date)		
WITNESS:	,	
Koichi kanai Printed Name	Signature	
4/1/2019		
(Jate)		

PATENT REEL: 048750 FRAME: 0711

RECORDED: 04/01/2019